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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSD226

Silicon Schottky Barrier Diode for High Speed Switching



ADE-208-1536A (Z)

Rev.1
Jul. 2002

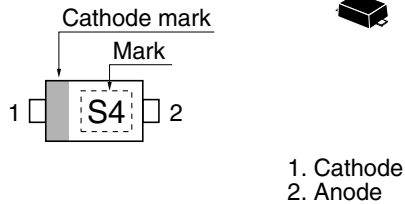
Features

- Low reverse current, Low capacitance.
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HSD226	S4	SFP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	25	V
Non-Repetitive Peak forward surge current	I_{FSM}^{*1}	200	mA
Forward current	I_F	50	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Note: 1. 10 ms Sine Wave 1 pulse

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.33	V	$I_F = 1 \text{ mA}$
	V_{F2}	—	—	0.38	V	$I_F = 5 \text{ mA}$
Reverse current	I_R	—	—	0.45	μA	$V_R = 20 \text{ V}$
Capacitance	C	—	—	2.80	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$

Note: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

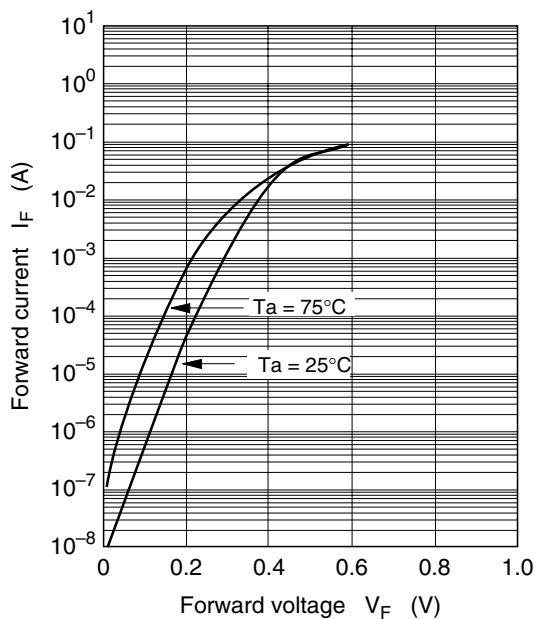


Fig.1 Forward current vs. Forward voltage

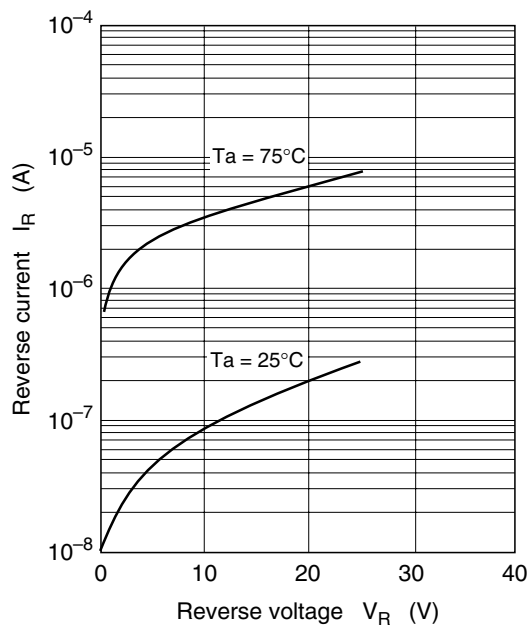


Fig.2 Reverse current vs. Reverse voltage

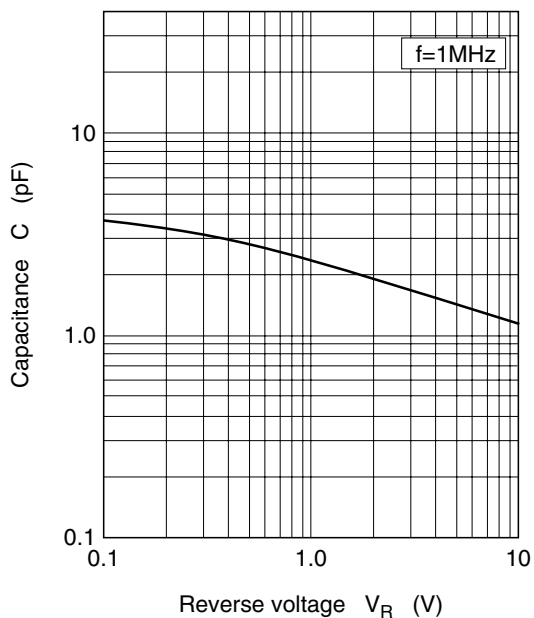
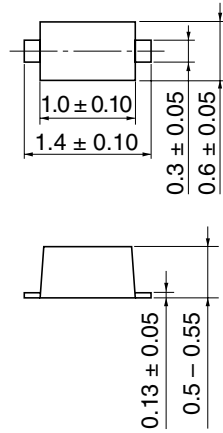


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2002

Unit: mm



Hitachi Code	SFP
JEDEC	—
JEITA	—
Mass (reference value)	0.0010 g

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